



Product Change Notification

Change Notification #: 116483 - 01
Change Title: Intel® Server Chassis H2204XXLRE
Intel® Server Chassis H2204XXNPS,
Intel® Server Chassis H2216XXKR2,
Intel® Server Chassis H2216XXLR2,
Intel® Server Chassis H2224XXLR2,
Intel® Server Chassis H2312XXKR2,
Intel® Server Chassis H2312XXLR2,
Intel® Server Chassis H2312XXLR3,
Intel® Server Chassis H2312XXNPS,
PCN 116483-01, Product Design,
Hot Swap Back Plane Firmware Update,
Reason for Revision: Correction to TA numbers for H2204XXLRE

Date of Publication: March 4, 2019

Key Characteristics of the Change:
Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:*	October 5, 2018
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** Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.*

Description of Change to the Customer:

Reason for Revision: Correction to TA numbers for H2204XXLRE

Intel is updating the Hot Swap Back Plane (HSBP) Firmware on the Intel® Server Chassis listed in the "Products Affected" table below. PSOC FW 1.41 is the new version installed from Factory

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation.

Customers can download and evaluate the PSOC Firmware Release integrated in the latest BIOS/ME/Integrated BMC and FRUSDR package posted at <http://www.intel.com/support>.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
H2216XXKR2	933688	H20866-014	H20866-015
E2312XXKR2	937161	H20865-014	H20865-015
H2312XXLR2	942352	J17277-008	J17277-009
H2216XXLR2	942353	H95607-008	H95607-009
H2224XXLR2	943577	H96144-007	H96144-008
H2312XXLR3	954487	J57869-003	J57869-004
H2204XXLRE	957322	J32925-007	J32925-008
H2312XXNPS	976841	J92610-001	J92610-002
H2204XXNPS	976843	J92613-001	J92613-002

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
September 18, 2018	00	Originally Published PCN
March 4, 2019	01	Correction to TA numbers for H2204XXLRE



Product Change Notification

116483 - 01

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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